

In The Claims

Claim 1 has been amended as follows:

Sub
B1
A1

1. (Amended) A matrix form semiconductor package substrate having an electrode situated in-between a plurality of integrated circuit (IC) package substrates for providing electrical communication to conductive pads situated on the substrate comprising:

a plurality of IC package substrates integrally formed on a substrate strip in a matrix form having a boundary between each two of said plurality of IC package substrates, each of said plurality of IC package substrates having a multiplicity of conductive pads; and

an electrode formed in a rectangular-shaped, serpentine configuration along said boundary for providing electrical communication to said multiplicity of conductive pads and for providing insulation between said multiplicity of conductive pads after said plurality of IC packages are cut along said boundary through said electrode.

Claim 11 has been amended as follows:

Sub
B2
A2

11. (Amended) A ball grid array package substrate comprising:
an insulating substrate having a top surface;
a plurality of BGA package substrates formed on said top surface of said insulating substrate;
a multiplicity of conductive traces emanating from each one of said plurality of BGA package substrates, each of said multiplicity of conductive traces provides electrical communication between a conductive pad and a wirebond finger situated on a BGA package; and
an electrode having a rectangular-shaped, serpentine configuration electrically connected to said multiplicity of conductive traces.

REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.